

Tilt Sensor Switch

Item No.	RBS050300T	Description	Tilt Sensor Switch	Version	13
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● FUNCTION

45° Tilt Detecting within a 360° radius.

● APPLICATIONS

1. Wake up systems for power saving, such like remote controllers.
2. Anti-theft / Anti-tamper devices
3. Rotation detection for monitors
4. Alarm system
5. Earthquake detecting
6. Toys / Entertainment device



● FEATURES

1. Suitable for vertical PCB.
2. Switch state : Normal open.
3. Gold-plated ball and terminals, low possibility of oxidization.
4. Housing made of high insulation plastic material, free from electric conduction and rust problem.
5. All plastic materials subject to industrial purpose, resist high temperature.
6. Simple ON and OFF signals, easy for design.
7. RoHS compliance, an ideal substitute for mercury switch.
8. A more economical tilt detection option than IC design solution.
9. All made in Taiwan and examined before shipment.

● PATENT

1. Taiwan Patent No. 226086

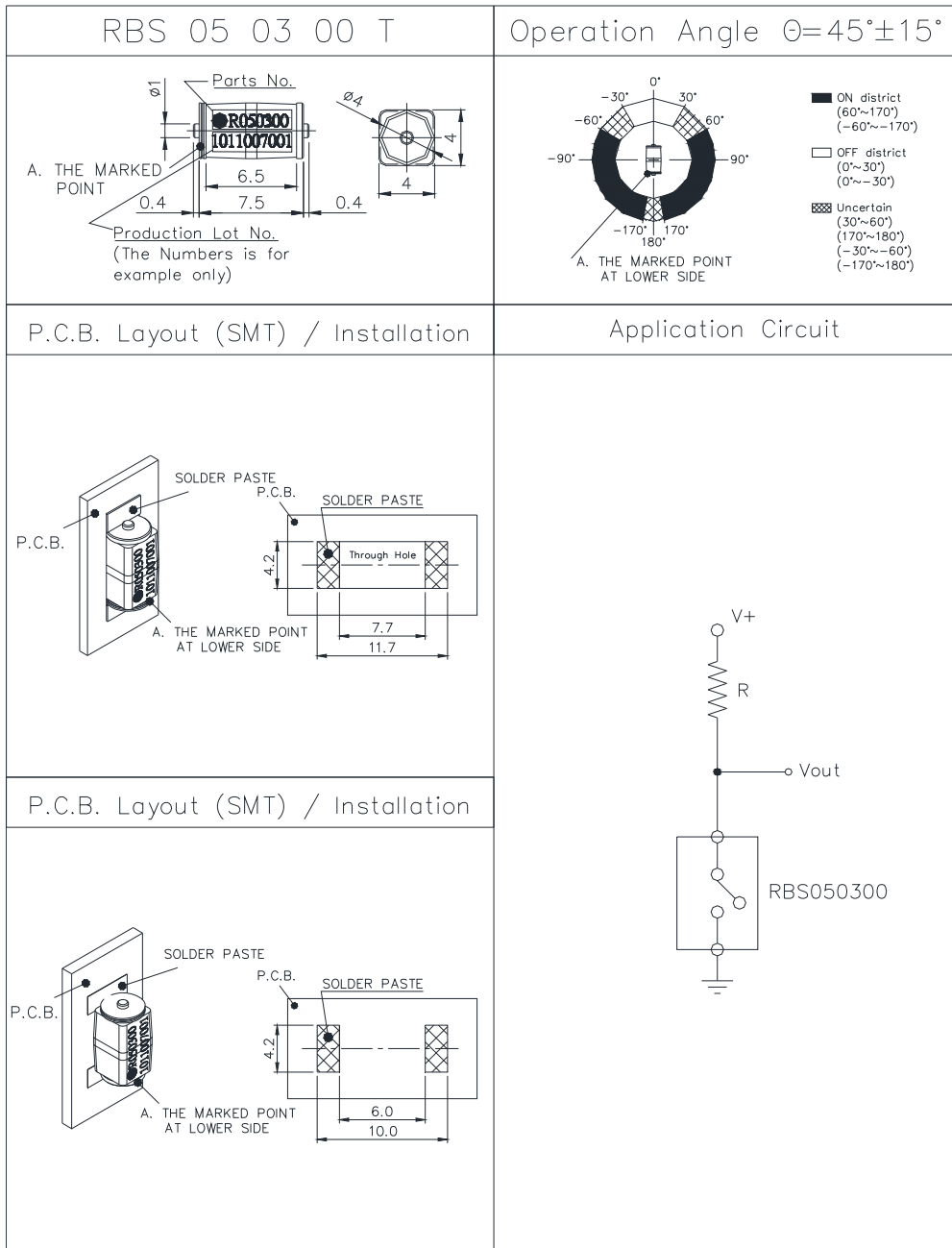


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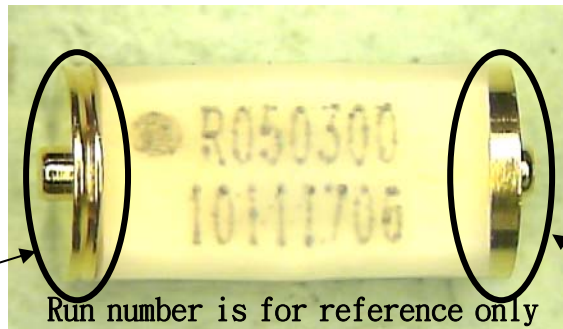
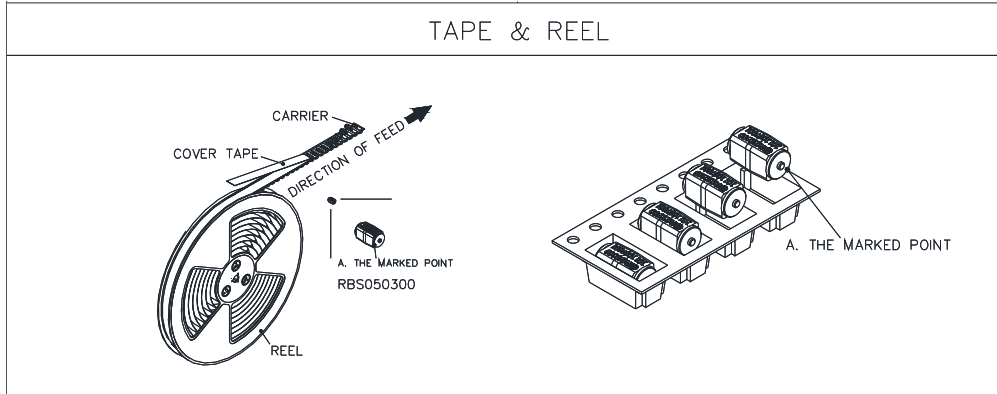
● DIMENSIONS / OPERATION / P.C.B. LAYOUT (Unit: mm, Tolerance: $\pm 0.25\text{mm}$)

Fig. 1



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Terminal with foolproof V-type groove is downward.

Terminal without groove is upward.

● Current/Voltage Suggested

Input Current (mA)	Operating Voltage (V)	Condition
1.0	5	--



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● ELECTRICAL CHARACTERISTICS

1	Contact Rating	10 mA · 5 VDC
2	Contact Resistance	50 Ω max.
3	Dielectric Strength	Refer to Fig. 1
4	Insulation Resistance	1000 MΩ min. · 100 VDC
5	Dielectric Strength	50 VDC min. · 1 minute
6	Capacitance	5 pF max.
7	Conductive Rate	90% min.

● RELIABILITY TEST ITEMS

Reliability Test for RBS050300T

Test Item	Standard	Contents
IR Reflow	MIL-STD-202G, TEST METHOD 210F · IPC/JEDEC J-STD-020D	Peak temp.=255~260°C*3times
Operating Temperature	MIL-STD-202G, TEST METHOD 107G, TEST A	-25°C~85°C
Storage Temperature	MIL-STD-202G, TEST METHOD 107G, TEST A	-40°C~85°C
Humidity	MIL-STD-202G, TEST METHOD 103B	40°C/95%RH
Mechanical Life	--	2 Hz horizontal 1,000,000 times
Electrical Life	--	100,000 times



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● SOLDERING CONDITION

Following soldering conditions are for reference only, please use soldering information that solder paste manufacturer recommends.

Condition Operation Method	Soldering Temperature	Soldering Time	Wattage of Manual Soldering	Suitable Production Process
IR Reflow	Please refer to following < Table of classification Reflow profile > and Fig. 2		-	SMT
Wave Soldering	260±5°C	< 5 seconds max.	-	DIP
Manual Soldering	260±5°C	< 5 seconds max.	20W or Temperature-controlled manual soldering	DIP · SMT



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< Table of classification Reflow profile >

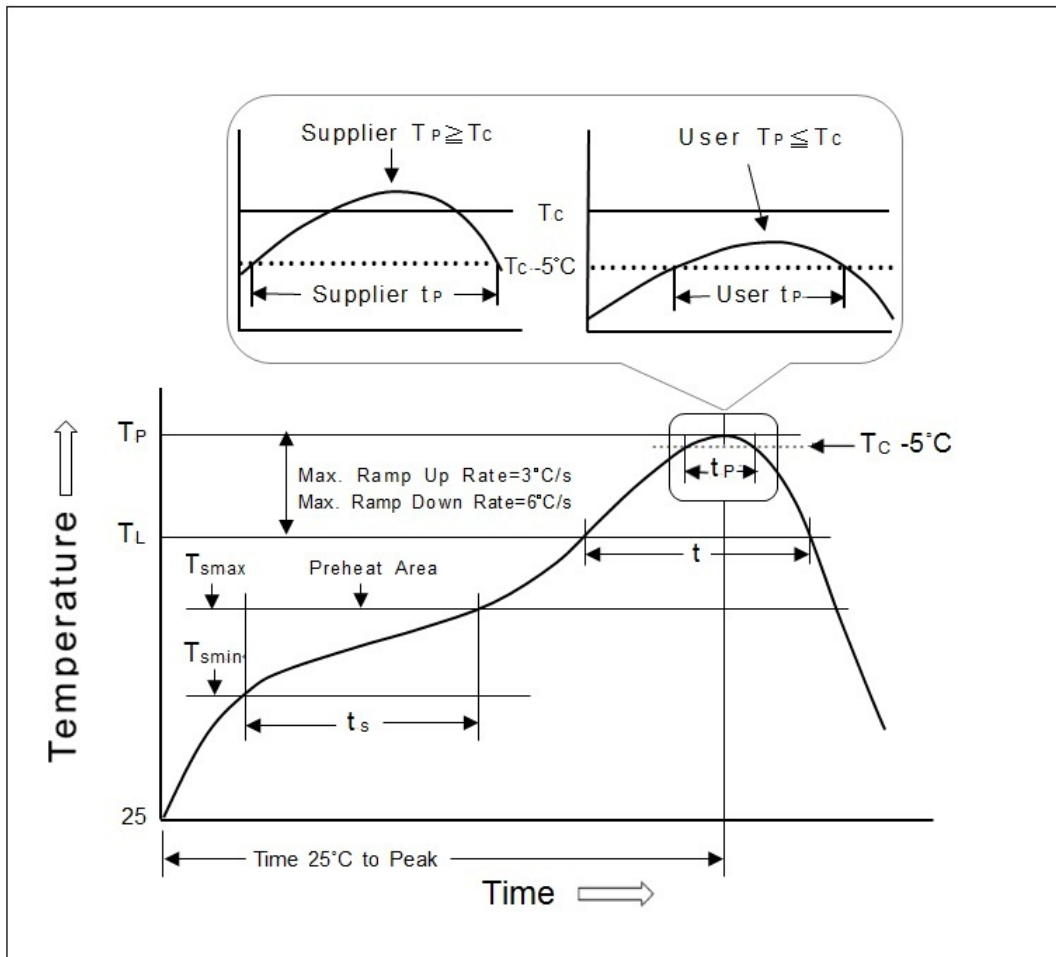
Item	Pb process	Pb free process
Pre-heat and Soak Temperature min.(T _{min}) Temperature max.(T _{max}) Time (T _{min} to T _{max})(t _s)	100 °C 150 °C 60-120 seconds	150 °C 200 °C 60-120 seconds
Average Rate of temperature rising up (T _{max} to T _p)	3 °C/second max.	3 °C/second max.
Liquidous Temperature (TL) Time at Liquidous (tL)	183 °C 60-150 seconds	217 °C 60-150 seconds
Peak package body Temperature (T _p)*	230 °C ~235 °C *	255 °C ~260 °C *
Classification temperature(T _c)	235 °C	260 °C
Time(tp)** within 5 °C of the specified classification temperature (T _c)	20** seconds	30** seconds
Average ram-down Rate (T _p to T _{max})	6 °C/second max.	6 °C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.
* Tolerance for peak profile temperature (T _p) is defined as a supplier minimum and a user maximum. ** Tolerance for time at peak profile temperature (tp) is defined as a supplier minimum and a user maximum.		



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Fig. 2



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● PACKAGE

	Part Number	Package	Quantity	Total	Size(mm)
1.	RBS050300	PE bag	1,000 pcs	1,000 pcs	205L*145W
		Inner box	10PE bag	10,000 pcs	348L*191W*85H
		Carton	3 boxes	30,000 pcs	364L*278W*213H

※ Package shown as below for reference.



	Part Number	Package	Quantity	Total	Size(mm)
2.	RBS050300T	Tape & reel	2,000 pcs	2,000 pcs	φ330*25H
		Inner box	2 reels	4,000 pcs	355L*340W*68H
		Carton	10 boxes	40,000 pcs	705L*365W*375H

※ Package shown as below for reference.



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● NOTE

1. Suggestion for usage : For vibration usage or application , we suggest to add hysteresis for IC; if vibration is heavy , optical type of sensor switch is recommended.
2. For the continued product improvement as one of the company policy, specifications may change or update without notice. The latest information can be obtained through our sales offices. Normally, all products are supplied under our standard conditions.

● PRECAUTIONS FOR USE

1. If the products is intended to be used for other endurance equipment requiring higher safety and reliability such as life support system, space and aviation devices, disaster and safety system, it's necessary to make verification of conformity or contact us for the details before using.
2. Do not try to clean the switch with a solvent or similar substance after the soldering process.
3. Use water-soluble flux may damage the switch.
4. If soldering temperature exceeds our specification, sensor switch could get apart.
5. Do not use switch in the environment of high humidity , because such an environment may cause the leakage current between the terminals.
6. More than the rated load may cause fire, so do not use more than the load.
7. In the circuit , switch should not be near or directly connected with the magnetic component solder joints (for example: relays, transformers, etc.).

